

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	788	257/782.ccls. or 257/783.ccls.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:09			0
2	BRS	L2	134	L1 and(die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:11			0
3	BRS	L3	134	L1 and (die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:11			0
4	BRS	L4	1	L3 and (bismaleimide near adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:15			0
5	BRS	L5	1	substrate and die and (bismaleimide with adhesive) and (solder adj mask)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:19			0
6	BRS	L6	129	substrate and die and (bismaleimide same adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:19			0
7	BRS	L7	46	substrate and die and (bismaleimide with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:25			0
8	BRS	L8	2	L7 and ((prevent or enhance or improve or benefit) with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:28			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9	BRS	L9	0	L7 and ((prevent or enhance or improve or benefit) with (bmi or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:29			0
10	BRS	L10	0	L7 and ((prevent or enhance or improve or benefit) same (bmi or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:29			0
11	BRS	L11	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:51			0
12	BRS	L12	8	L11 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
13	BRS	L13	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismalamide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
14	BRS	L14	8	L13 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:53			0
15	BRS	L15	247	(adhesive with (bmi or bism\$)) and (prevent or improve or increase or advantage or benefit)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:39		Truncation Overflow. Return string from Server is: 5'660354'	1
16	BRS	L16	87	L15 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:55			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	L17	3	(adhesive with (bmi or bism\$)) with (moisture or break\$)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:42		Truncation Overflow. Return string from Server is: 5'660354'	1

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	788	257/782.ccls. or 257/783.ccls.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:09			0
2	BRS	L2	134	L1 and(die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:11			0
3	BRS	L3	134	L1 and (die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:11			0
4	BRS	L4	1	L3 and (bismaleimide near adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:15			0
5	BRS	L5	1	substrate and die and (bismaleimide with adhesive) and (solder adj mask)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:19			0
6	BRS	L6	129	substrate and die and (bismaleimide same adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:19			0
7	BRS	L7	46	substrate and die and (bismaleimide with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:25			0
8	BRS	L8	2	L7 and ((prevent or enhance or improve or benefit) with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:28			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9	BRS	L9	0	L7 and ((prevent or enhance or improve or benefit) with (bmi or bismaleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:29			0
10	BRS	L10	0	L7 and ((prevent or enhance or improve or benefit) same (bmi or bismaleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:29			0
11	BRS	L11	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismaleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:51			0
12	BRS	L12	8	L11 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
13	BRS	L13	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismalamide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
14	BRS	L14	8	L13 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:53			0
15	BRS	L15	247	(adhesive with (bmi or bism\$)) and (prevent or improve or increase or advantage or benefit)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:39		Truncation Overflow. Return string from Server is: 5`660354`	1
16	BRS	L16	87	L15 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:55			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	L17	3	(adhesive with (bmi or bism\$)) with (moisture or break\$)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:42		Truncation Overflow. Return string from Server is: 5'660354`	1
18	BRS	L18	25	257/783.ccls. and (bmi or bism\$)	USPAT	2001/09/19 14:35			0
19	BRS	L19	228	(adesion or adhesive)with (bmi or bism\$)	USPAT	2001/09/19 14:07			0
20	BRS	L20	372	(adhesion or adhesive)with (bmi or bism\$)	USPAT	2001/09/19 14:13			0
21	BRS	L21	88	L20 and semiconductor	USPAT	2001/09/19 14:08			0
22	BRS	L22	44	L20 and mask	USPAT	2001/09/19 14:08			0
23	BRS	L23	273	L20 and (substrate or carrier)	USPAT	2001/09/19 14:33			0
24	BRS	L24	410	(chip or die) and (solder adj mask) and adhesive	USPAT	2001/09/19 14:34			0
25	BRS	L25	61	L24 and (bmi or bism\$)	USPAT	2001/09/19 14:35			0